











Delphi Series V36SE, 1/16th Brick DC/DC Power Modules: 18~75Vin, up to 50W

The Delphi Series V36SE, 1/16th Brick, 18~75V wide input, single output, isolated DC/DC converter, is the latest offering from a world leader in power systems technology and manufacturing — Delta Electronics, Inc. This product family provides up to 50 watts of power in the industry standard 1/16th brick form factor (1.30"x0.90") and pinout. With creative design technology and optimization of component placement, these converters possess outstanding electrical and thermal performance, as well as extremely high reliability under highly stressful operating conditions. For the 12V output module, it delivers 50W (4.2A) output with 36 to 75V input and delivers 40W (3.5A) output while the input is 18 to 36V to the same module. Typical efficiency of the 12V/4.2A module is greater than 88%. All modules are protected from abnormal input/output voltage, current, and temperature conditions. For lower power needs, but in a similar small form factor, please check out Delta S48SP (36W or 10A) and S36SE (17W or 5A) series standard DC/DC modules.

FEATURES

- High efficiency: 88% @ 12V/4.2A, 48Vin 86% @ 12V/3.5A, 24Vin
- Size: 33.0x22.8x8.7mm (1.30"x0.90"x0.34")
- Industry standard 1/16th brick size & pinout
- Input UVLO
- OTP and output OCP, OVP (default is auto-recovery)
- Output voltage trim: -20%, +10%
- Monotonic startup into normal and pre-biased loads
- 2250V isolation and basic insulation
- No minimum load required
- SMD and Through-hole versions
- ISO 9001, TL 9000, ISO 14001, QS 9000, OHSAS 18001 certified manufacturing facility
- UL/cUL 60950-1 (US & Canada) Recognized

OPTIONS

- SMD pins
- Positive remote On/Off
- OTP and output OVP, OCP mode (Auto-restart or latch)

Soldering method

- Wave soldering
- Hand soldering
- · Reflow soldering

APPLICATIONS

- Optical Transport
- Data Networking
- Communications
- Servers



TECHNICAL SPECIFICATIONS

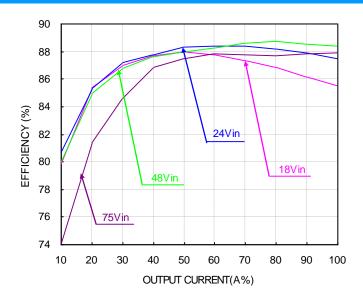
(T_A =25 °C, airflow rate=300 LFM, V_{in} =48Vdc, nominal Vout unless otherwise noted.)

PARAMETER	NOTES and CONDITIONS	V36SE12004(Standard)			
		Min.	Тур.	Max.	Units
ABSOLUTE MAXIMUM RATINGS					\/- -
Input Voltage Continuous				80	Vdc Vdc
Transient (100ms)	100ms			100	Vdc
Operating Temperature	Refer to figure 19 for measuring point	-40		122	°C
Storage Temperature	reserve figure to ter measuring point	-55		125	°C
Input/Output Isolation Voltage				2250	Vdc
INPUT CHARACTERISTICS					
Operating Input Voltage		18	48	75	Vdc
Input Under-Voltage Lockout					
Turn-On Voltage Threshold		16	17	18	Vdc
Turn-Off Voltage Threshold Lockout Hysteresis Voltage		15	16	17	Vdc
Maximum Input Current	100% Load, 18Vin	0.5	1	1.8 3.9	Vdc A
No-Load Input Current	100 % LOau, 18 VIII		20	3.9	mA
Off Converter Input Current			8		mA
Inrush Current (I ² t)			Ü	1	A ² s
Input Reflected-Ripple Current	P-P thru 12µH inductor, 5Hz to 20MHz		10		mA
Input Voltage Ripple Rejection	120 Hz		50		dB
OUTPUT CHARACTERISTICS					
Output Voltage Set Point	Vin=48V, Io=Io.max, Tc=25°C	11.88	12.00	12.12	Vdc
Output Voltage Regulation					
Over Load	lo=lo, min to lo, max		±3	±12	mV
Over Line	Vin=36V to 75V		±3	±12	mV
Over Temperature	Tc=-40°C to 85°C		±120	10.00	mV
Total Output Voltage Range	Over sample load, line and temperature	11.64	12.00	12.36	V
Output Voltage Ripple and Noise Peak-to-Peak	5Hz to 20MHz bandwidth Full Load, 1µF ceramic, 10µF tantalum		100	150	mV
RMS	Full Load, 1µF ceramic, 10µF tantalum Full Load, 1µF ceramic, 10µF tantalum		25	40	mV
Operating Output Current Range	Vin=18V-36V	0	23	3.5	A
Operating Output Current Range	Vin=36V-75V	0		4.2	A
Output Over Current Protection	Output Voltage 10% Low	110		140	%
DYNAMIC CHARACTERISTICS	0 tip to 10 tings 10 / 0 = 0 ti				,,
Output Voltage Current Transient	48V, 10μF Tan & 1μF Ceramic load cap, 0.1A/μs				
Positive Step Change in Output Current	25% lo.max to 50% lo.max		400		mV
Negative Step Change in Output Current	50% lo.max to 25% lo.max		400		mV
Settling Time (within 1% Vout nominal)			500		μs
Turn-On Transient					
Start-Up Time, From On/Off Control			30		ms
Start-Up Time, From Input	Full loads 50/ assessback of Vost at atastus		30	2000	ms
Maximum Output Capacitance (note1) EFFICIENCY	Full load; 5% overshoot of Vout at startup			2200	μF
100% Load	Vin=48V		88.0		%
100% Load	Vin=24V		86.0		%
60% Load	Vin=48V		88.0		%
ISOLATION CHARACTERISTICS					
Input to Output				2250	Vdc
Isolation Resistance		10			МΩ
Isolation Capacitance			1000		pF
FEATURE CHARACTERISTICS					
Switching Frequency			440		KHz
ON/OFF Control, Negative Remote On/Off logic	V/-#			0.0	- \/
Logic Low (Module On) Logic High (Module Off)	Von/off	2		0.8	V >
ON/OFF Control, Positive Remote On/Off logic	Von/off			18	V
Logic Low (Module Off)	Von/off			0.8	V
Logic Low (Module On) Logic High (Module On)	Von/off	2		18	V
ON/OFF Current (for both remote on/off logic)	Ion/off at Von/off=0.0V			1	mA
Leakage Current (for both remote on/off logic)	Logic High, Von/off=15V			50	μA
Output Voltage Trim Range	Pout ≦ max rated power,lo ≦ lo.max	-20		10	%
Output Voltage Remote Sense Range	Pout ≤ max rated power,lo ≤ lo.max			10	%
Output Over-Voltage Protection	Over full temp range; % of nominal Vout	120		150	%
GENERAL SPECIFICATIONS					
MTBF	lo=80% of lo, max; Ta=25°C, airflow		3.0		M hours
Weight			12.1		grams
Over-Temperature Shutdown	Refer to figure 19 for measuring point		129		°C

Note1: For applications with higher output capacitive load, please contact Delta



ELECTRICAL CHARACTERISTICS CURVES



6 POWER DISSIPATION(W) 5 48Vin 75Vin 4 3 2 1 0 10 20 30 40 50 60 70 80 90 100 OUTPUT CURRENT(A%)

24Vin

18Vin

8

7

Figure 1: Efficiency vs. load current for minimum, nominal, and maximum input voltage at 25°C 18V~36V, Iomax is 3.5A, 36V~75VIN, Iomax is 4.2A

Figure 2: Power dissipation vs. load current for minimum, nominal, and maximum input voltage at 25°C. 18V~36V, Iomax is 3.5A, 36V~75VIN, Iomax is 4.2A

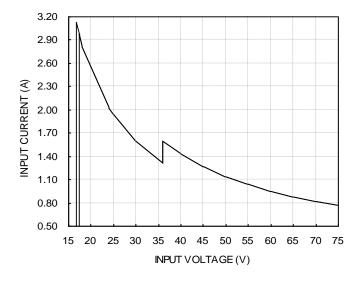


Figure 3: Typical full load input characteristics at room temperature



ELECTRICAL CHARACTERISTICS CURVES

For Negative Remote On/Off Logic

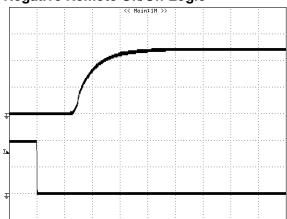


Figure 4: Turn-on transient at full rated load current (resistive load) (10 ms/div). Vin=48V. Top Trace: Vout, 5.0V/div; Bottom Trace: ON/OFF input, 2V/div

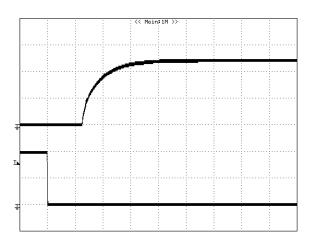


Figure 5: Turn-on transient at zero load current (10 ms/div). Vin=48V. Top Trace: Vout: 5.0V/div, Bottom Trace: ON/OFF input, 2V/div

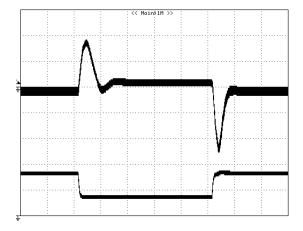


Figure 6: Output voltage response to step-change in load current (50%-25%-50% of lo, max; di/dt = 0.1A/μs; Vin is 24v). Load cap: 10μF tantalum capacitor and 1μF ceramic capacitor. Top Trace: Vout (200mV/div, 200us/div), Bottom Trace: lout (1A/div). Scope measurement should be made using a BNC cable (length shorter than 20 inches). Position the load between 51 mm to 76 mm (2 inches to 3 inches) from the module

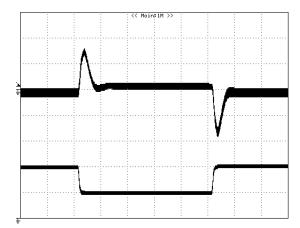


Figure 7: Output voltage response to step-change in load current (50%-25%-50% of lo, max; di/dt = 0.1A/ μ s; Vin is 48v). Load cap: 10 μ F tantalum capacitor and 1 μ F ceramic capacitor. Top Trace: Vout (200mV/div, 200us/div), Bottom Trace: lout (1A/div). Scope measurement should be made using a BNC cable (length shorter than 20 inches). Position the load between 51 mm to 76 mm (2 inches to 3 inches) from the module



ELECTRICAL CHARACTERISTICS CURVES

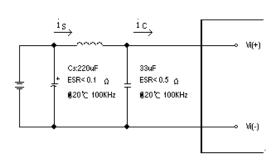


Figure 8: Test set-up diagram showing measurement points for Input Terminal Ripple Current and Input Reflected Ripple Current.

Note: Measured input reflected-ripple current with a simulated source Inductance (L_{TEST}) of 12 μ H. Capacitor Cs offset possible battery impedance. Measure current as shown above

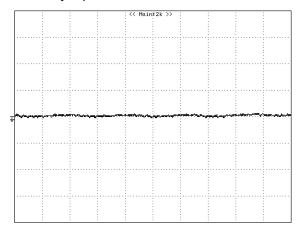


Figure 10: Input reflected ripple current, is, through a $12\mu H$ source inductor at nominal input voltage (vin=48v) and rated load current (20 mA/div, 1us/div)

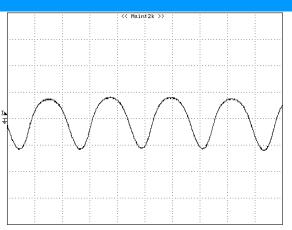


Figure 9: Input Terminal Ripple Current, i_c, at full rated output current and nominal input voltage (Vin=48v) with 12μH source impedance and 33μF electrolytic capacitor (200 mA/div, 1us/div)

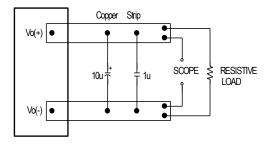


Figure 11: Output voltage noise and ripple measurement test setup



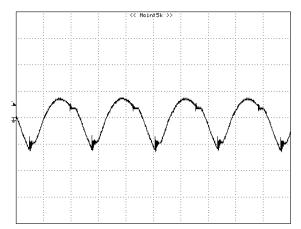


Figure 12: Output voltage ripple at nominal input voltage (vin=48v) and rated load current (lo=4.2A) (50 mV/div, 1us/div).Load capacitance: 1μF ceramic capacitor and 10μF tantalum capacitor. Bandwidth: 20 MHz. Scope measurements should be made using a BNC cable (length shorter than 20 inches). Position the load between 51 mm to 76 mm (2 inches to 3 inches) from the module

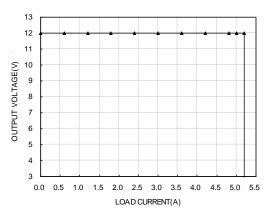


Figure 13: Output voltage vs. load current showing typical current limit curves and converter shutdown points (Vin=48v)



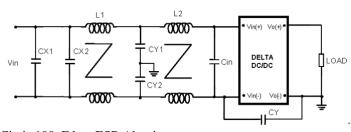
DESIGN CONSIDERATIONS

Input Source Impedance

The impedance of the input source connecting to the DC/DC power modules will interact with the modules and affect the stability. A low ac-impedance input source is recommended. If the source inductance is more than a few $\mu H,$ we advise adding a 10 to 100 μF electrolytic capacitor (ESR < 0.7 Ω at 100 kHz) mounted close to the input of the module to improve the stability.

Layout and EMC Considerations

Delta's DC/DC power modules are designed to operate in a wide variety of systems and applications. For design assistance with EMC compliance and related PWB layout issues, please contact Delta's technical support team. Below is the reference design for an input filter tested with V36SE12004XXXX to meet class B in CISSPR 22.



Cin is 100uF low ESR Aluminum cap; CX1 is 1uF ceramic cap;

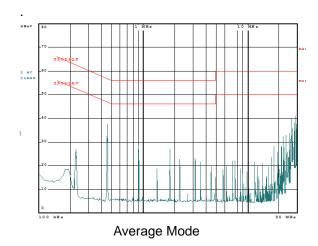
CX2 is 4.7uF ceramic cap;

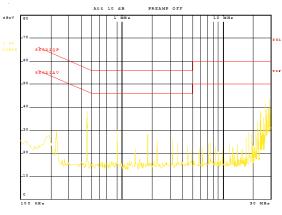
CY1 and CY2 are 4.7nF ceramic cap;

CY is 10nF ceramic cap;

L1 and L2 are common-mode inductors, L1=0.2mH L2=0.5mH

Test Result: Vin=48V, Io=4A





Peak Mode

Safety Considerations

The power module must be installed in compliance with the spacing and separation requirements of the end-user's safety agency standard, i.e., UL60950-1, CAN/CSA-C22.2, No. 60950-1 and EN60950-1+A11 and IEC60950-1, if the system in which the power module is to be used must meet safety agency requirements.

Basic insulation based on 75 Vdc input is provided between the input and output of the module for the purpose of applying insulation requirements when the input to this DC-to-DC converter is identified as TNV-2 or SELV. An additional evaluation is needed if the source is other than TNV-2 or SELV.

When the input source is SELV circuit, the power module meets SELV (safety extra-low voltage) requirements. If the input source is a hazardous voltage which is greater than 60 Vdc and less than or equal to 75 Vdc, for the module's output to meet SELV requirements, all of the following must be met:

- The input source must be insulated from the ac mains by reinforced or double insulation.
- The input terminals of the module are not operator accessible.
- If the metal baseplate is grounded, one Vi pin and one Vo pin shall also be grounded.
- A SELV reliability test is conducted on the system where the module is used, in combination with the module, to ensure that under a single fault,



When installed into a Class II equipment (without grounding), spacing consideration should be given to the end-use installation, as the spacing between the module and mounting surface have not been evaluated.

The power module has extra-low voltage (ELV) outputs when all inputs are ELV.

This power module is not internally fused. To achieve optimum safety and system protection, an input line fuse is highly recommended. The safety agencies require a normal-blow fuse with 5A maximum rating to be installed in the ungrounded lead. A lower rated fuse can be used based on the maximum inrush transient energy and maximum input current.

Soldering and Cleaning Considerations

Post solder cleaning is usually the final board assembly process before the board or system undergoes electrical testing. Inadequate cleaning and/or drying may lower the reliability of a power module and severely affect the finished circuit board assembly test. Adequate cleaning and/or drying is especially important for un-encapsulated and/or open frame type power modules. For assistance on appropriate soldering and cleaning procedures, please contact Delta's technical support team.



FEATURES DESCRIPTIONS

Over-Current Protection

The modules include an internal output over-current protection circuit, which will endure current limiting for an unlimited duration during output overload. If the output current exceeds the OCP set point, the modules will automatically shut down, and enter hiccup mode or latch mode, which is optional.

For hiccup mode, the module will try to restart after shutdown. If the over current condition still exists, the module will shut down again. This restart trial will continue until the over-current condition is corrected.

For latch mode, the module will latch off once it shutdown. The latch is reset by either cycling the input power or by toggling the on/off signal for one second.

Over-Voltage Protection

The modules include an internal output over-voltage protection circuit, which monitors the voltage on the output terminals. If this voltage exceeds the over-voltage set point, the module will shut down, and enter in hiccup mode or latch mode, which is optional.

For hiccup mode, the module will try to restart after shutdown. If the over voltage condition still exists, the module will shut down again. This restart trial will continue until the over-voltage condition is corrected.

For latch mode, the module will latch off once it shutdown. The latch is reset by either cycling the input power or by toggling the on/off signal for one second.

Over-Temperature Protection

The over-temperature protection consists of circuitry that provides protection from thermal damage. If the temperature exceeds the over-temperature threshold the module will shut down, and enter in hiccup mode or latch mode, which is optional.

For hiccup mode, the module will try to restart after shutdown. If the over temperature condition still exists, the module will shut down again. This restart trial will continue until the over-temperature condition is corrected.

For latch mode, the module will latch off once it shutdown. The latch is reset by either cycling the input power or by toggling the on/off signal for one second.

Remote On/Off

The remote on/off feature on the module can be either negative or positive logic. Negative logic turns the module on during a logic low and off during a logic high. Positive logic turns the modules on during a logic high and off during a logic low.

Remote on/off can be controlled by an external switch between the on/off terminal and the Vi(-) terminal. The switch can be an open collector or open drain.

For negative logic if the remote on/off feature is not used, please short the on/off pin to Vi(-). For positive logic if the remote on/off feature is not used, please leave the on/off pin floating.

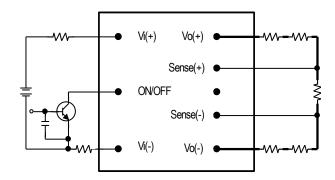


Figure 14: Remote on/off implementation

Remote Sense

Remote sense compensates for voltage drops on the output by sensing the actual output voltage at the point of load. The voltage between the remote sense pins and the output terminals must not exceed the output voltage sense range given here:

$$[Vo(+) - Vo(-)] - [SENSE(+) - SENSE(-)] \le 10\% \times Vout$$

This limit includes any increase in voltage due to remote sense compensation and output voltage set point adjustment (trim).

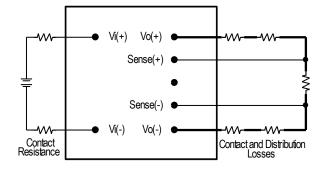


Figure 15: Effective circuit configuration for remote sense operation



FEATURES DESCRIPTIONS (CON.)

If the remote sense feature is not used to regulate the output at the point of load, please connect SENSE(+) to Vo(+) and SENSE(-) to Vo(-) at the module.

The output voltage can be increased by both the remote sense and the trim; however, the maximum increase is the larger of either the remote sense or the trim, not the sum of both.

When using remote sense and trim, the output voltage of the module is usually increased, which increases the power output of the module with the same output current.

Care should be taken to ensure that the maximum output power does not exceed the maximum rated power.

Output Voltage Adjustment (TRIM)

To increase or decrease the output voltage set point, connect an external resistor between the TRIM pin and either the SENSE(+) or SENSE(-). The TRIM pin should be left open if this feature is not used.

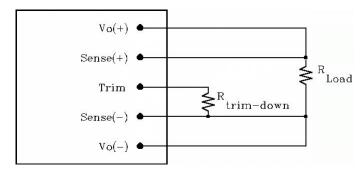


Figure 16: Circuit configuration for trim-down (decrease output voltage)

If the external resistor is connected between the TRIM and SENSE (-) pins, the output voltage set point decreases (Fig. 18). The external resistor value required to obtain a percentage of output voltage change Δ % is defined as:

$$Rtrim - down = \left\lceil \frac{511}{\Lambda} - 10.2 \right\rceil (K\Omega)$$

Ex. When Trim-down -10% (12Vx0.9=10.8V)

$$Rtrim - down = \left[\frac{511}{10} - 10.2\right] (K\Omega) = 40.9 (K\Omega)$$

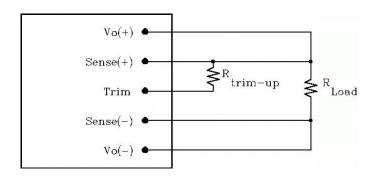


Figure 17: Circuit configuration for trim-up (increase output voltage)

If the external resistor is connected between the TRIM and SENSE (+) the output voltage set point increases (Fig. 19). The external resistor value required to obtain a percentage output voltage change Δ % is defined as:

$$Rtrim - up = \frac{5.11 \text{Vo} (100 + \Delta)}{1.225 \Delta} - \frac{511}{\Delta} - 10.2 (K\Omega)$$

Ex. When Trim-up +10% (12Vx1.1=13.2V)

$$Rtrim - up = \frac{5.11 \times 12 \times (100 + 10)}{1.225 \times 10} - \frac{511}{10} - 10.2 = 489.3 (K\Omega)$$

The output voltage can be increased by both the remote sense and the trim, however the maximum increase is the larger of either the remote sense or the trim, not the sum of both.

When using remote sense and trim, the output voltage of the module is usually increased, which increases the power output of the module with the same output current.

Care should be taken to ensure that the maximum output power of the module remains at or below the maximum rated power.



THERMAL CONSIDERATIONS

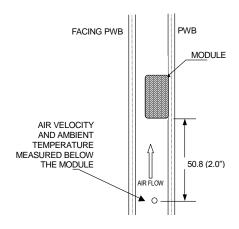
Thermal management is an important part of the system design. To ensure proper, reliable operation, sufficient cooling of the power module is needed over the entire temperature range of the module. Convection cooling is usually the dominant mode of heat transfer.

Hence, the choice of equipment to characterize the thermal performance of the power module is a wind tunnel.

Thermal Testing Setup

Delta's DC/DC power modules are characterized in heated vertical wind tunnels that simulate the thermal environments encountered in most electronics equipment. This type of equipment commonly uses vertically mounted circuit cards in cabinet racks in which the power modules are mounted.

The following figure shows the wind tunnel characterization setup. The power module is mounted on a test PWB and is vertically positioned within the wind tunnel. The space between the neighboring PWB and the top of the power module is constantly kept at 6.35mm (0.25").



Note: Wind Tunnel Test Setup Figure Dimensions are in millimeters and (Inches)

Figure 18: Wind tunnel test setup

Thermal Derating

Heat can be removed by increasing airflow over the module. To enhance system reliability, the power module should always be operated below the maximum operating temperature. If the temperature exceeds the maximum module temperature, reliability of the unit may be affected.

THERMAL CURVES

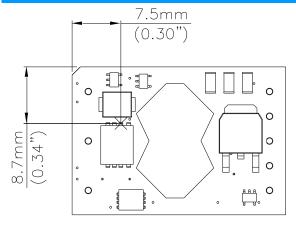


Figure 19: Temperature measurement location
* The allowed maximum hot spot temperature is defined at 122°C.

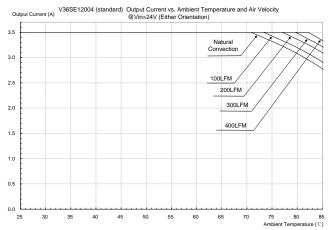


Figure 20: Output current vs. ambient temperature and air velocity @ V_{in}=24V (Either Orientation)

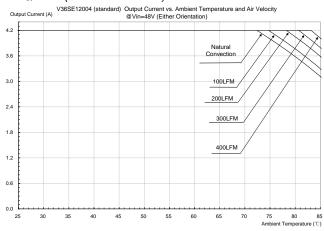
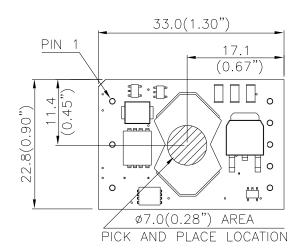


Figure 21: Output current vs. ambient temperature and air velocity @ V_{in}=48V (Either Orientation)



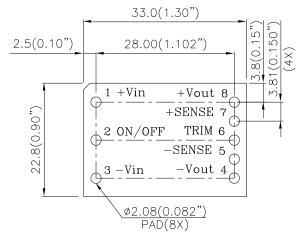
PICK AND PLACE LOCATION

RECOMMENDED PAD LAYOUT (SMD)



NOTES:

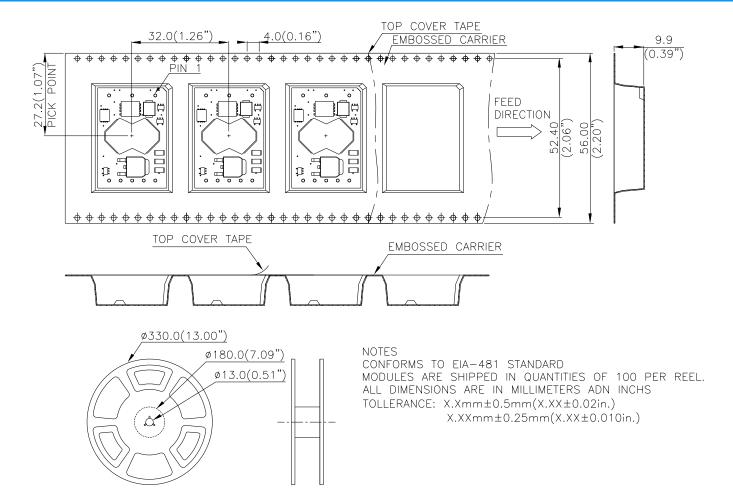
DIMENSIONS ARE IN MILLIMETERS AND (INCHES) TOLERANCES: X.Xmm±0.5mm(X.XX in.±0.02 in.) X.XXmm±0.25mm(X.XXX in.±0.010 in.)



RECOMENDED P.W.B PAD LAYOUT NOTES:

DIMENSIONS ARE IN MILLIMETERS AND (INCHES) TOLERANCES: X.Xmm±0.5mm(X.XX in.±0.02 in.) $X.XXmm\pm0.25mm(X.XXX in.\pm0.010 in.)$

SURFACE-MOUNT TAPE & REEL

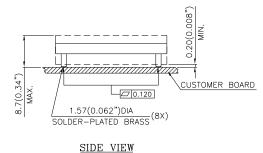




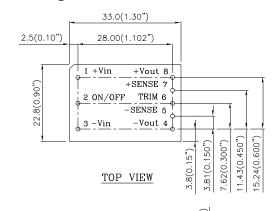
MECHANICAL DRAWING

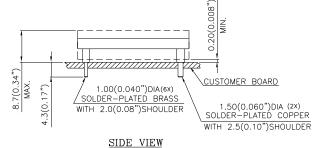
Surface-mount module

33.0(1.30") 28.00(1.102") 28.00(0.102") 1 +Vin +Vout 8 +SENSE 7 +SENSE 5 -SENSE 5



Through-hole module





NOTES:

DIMENSIONS ARE IN MILLIMETERS AND (INCHES)
TOLERANCES: X.Xmm±0.5mm(X.XX in.±0.02 in.)
X.XXmm±0.25mm(X.XXX in.±0.010 in.)

<u>Name</u>	<u>Function</u>		
+Vin	Positive input voltage		
ON/OFF	Remote ON/OFF		
-Vin	Negative input voltage		
-Vout	Negative output voltage		
-SENSE	Negative remote sense		
TRIM	Output voltage trim		
+SENSE	Positive remote sense		
+Vout	Positive output voltage		
	+Vin ON/OFF -Vin -Vout -SENSE TRIM +SENSE		



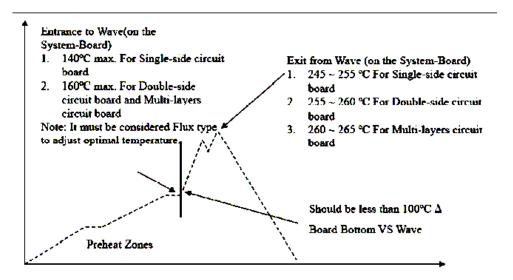
Soldering method

Generally, as the most common mass soldering method for the solder attachment, wave soldering is used for through-hole power modules and reflow soldering is used for surface-mount ones. Delta recommended soldering methods and process parameters are provided in this document for solder attachment of power modules onto system board. SAC305 is the suggested lead-free solder alloy for all soldering methods.

Reflow soldering is not a suggested method for through-hole power modules due to many process and reliability concerns. If you have this kind of application requirement, please refer to the last page "part numbering system", the P/N marked "PIH" means support reflow process. Or contact Delta sales/FAE for further confirmation.

Wave Soldering (Lead-free)

Delta's power modules are designed to be compatible with single-wave or dual wave soldering. The suggested soldering process must keep the power module's internal temperature below the critical temperature of 217°C continuously. The recommended wave-soldering profile is shown in following figure.



Recommended Temperature Profile for Lead-free Wave Soldering Note: The temperature is measured on solder joint of pins of power module.

The typical recommended (for double-side circuit board) preheat temperature is 115+/-10°C on the top side (component side) of the circuit board. The circuit-board bottom-side preheat temperature is typically recommended to be greater than 135°C and preferably within 100°C of the solder-wave temperature. A maximum recommended preheat up rate is 3°C/s. A maximum recommended solder pot temperature is 255+/-5°C with solder-wave dwell time of 3~6 seconds. The cooling down rate is typically recommended to be 6°C/s maximum.



Hand Soldering (Lead Free)

Hand soldering is the least preferred method because the amount of solder applied, the time the soldering iron is held on the joint, the temperature of the iron, and the temperature of the solder joint are variable. The recommended hand soldering guideline is listed in Table 1. The suggested soldering process must keep the power module's internal temperature below the critical temperature of 217°C continuously.

Parameter
Single-side
Circuit Board
Circuit Board
Circuit Board
Circuit Board
Soldering Iron Wattage
Tip Temperature
Single-side
Circuit Board
Circuit Board
90
90
90
420+/-10°C
420+/-10°C

 $2 \sim 6$ seconds

Table 1 Hand-Soldering Guideline

 $4 \sim 10$ seconds

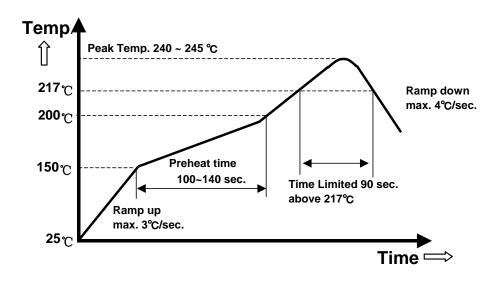
 $4 \sim 10$ seconds

Reflow Soldering (Lead-free)

Soldering Time

High temperature and long soldering time will result in IMC layer increasing in thickness and thereby shorten the solder joint lifetime. Therefore the peak temperature over 245°C is not suggested due to the potential reliability risk of components under continuous high-temperature. In the meanwhile, the soldering time of temperature above 217°C should be less than 90 seconds. Please refer to following figure for recommended temperature profile parameters.

Shielding cap is requested to mount on DCDC module if with heat-spreader/heat-sink, to prevent the customer side high temperature of reflow to re-melt the DCDC module's internal component's soldering joint.



Recommended Temperature Profile for Lead-free Reflow Soldering Note: The temperature is measured on solder joint of pins of power module.



PART NUMBERING SYSTEM									
V	36	S	Е	120	04	N	R	F	Α
Type of Product	Input Voltage	Number of Outputs	Product Series	Output Voltage	Output Current	ON/OFF Logic	Pin Length/Type		Option Code
V - 1/16 Brick	36 - 18V~75 V	S - Single	E - Regular	120 - 12V	04 - 4.2A	N- Negative P- Positive	K - 0.110" M - SMD N - 0.145" R - 0.170"	Space - RoHS 5/6 F - RoHS 6/6 (Lead Free)	A-Standard Functions

MODEL LIST									
MODEL NAME	INPUT		OUTPUT		EFF @ 100% LOAD				
V36SE12004NKFA	18V~75V	3.9A	12V	3.5A (18~36Vin) & 4.2A(36~75Vin)	86.0% @ 24Vin, 88.0% @ 48Vin				
V36SE12004NMFA	18V~75V	3.9A	12V	3.5A (18~36Vin) & 4.2A(36~75Vin)	86.0% @ 24Vin, 88.0% @ 48Vin				
V36SE12004NNFA	18V~75V	3.9A	12V	3.5A (18~36Vin) & 4.2A(36~75Vin)	86.0% @ 24Vin, 88.0% @ 48Vin				
V36SE12004NRFA	18V~75V	3.9A	12V	3.5A (18~36Vin) & 4.2A(36~75Vin) 4.2A(36~75Vin) (18~36Vin)	86.0% @ 24Vin, 88.0% @ 48Vin				

Default remote on/off logic is negative and pin length is 0.170"

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